Specifications

Drawing No.	USY1N-H1-13169-00 1/7
Issued Date.	Jul,8,2013

Messrs: Digi-Key

Note: In case of specification change, KYOCERA Part Number also will be changed.

Product Name	Tuning Fork Crystal
Product Model	ST3215SB
Frequency	32.768 kHz
Customer Part Number	-
Customer Specification Number	-
KYOCERA Part Number	ST3215SB32768B0HPWB3
Remarks Pb-Free, RoHS Compliant, MSL	.1

Customer Acceptance

Accept Signature	Approved Date	
	Department	
	Person in charge	

Seller

KYOCERA Corporation

6 Takeda Tobadono-cho, Fushimi-ku, Kyoto

612-8501 Japan

TEL. No. 075-604-3500 FAX. No. 075-604-3501 Manufacturer

KYOCERA Crystal Device Corporation

(Crystal Units Division)

5850, Higashine-koh, Higashine-shi, Yamagata

999-3701 Japan

TEL. No. 0237-43-5611

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Design Department	Quality Assurance	Approved by	Checked by	Issued by
KYOCERA Crystal Device Corporation	F.Mukae	T.Soda	A.Muraoka	Y.Nozaki
Crystal Unit Application Engineering Section				
Crystal Units Division				

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Revision History

Rev.No.	Description of revise	Date	Approved by	Checked by	Issued by
0	First Edition	Jul,8,2013	T.Soda	A.Muraoka	Y.Nozaki
1					

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1. APPLICATION

This specification sheet is applied to tuning fork crystal "ST3215SB".

2. PART NUMBER

ST3215SB32768B0HPWB3

3. RATINGS

Items	SYMB.	Rating	Unit
Operating Temperature	Topr	-40~+85	deg. C
Storage Temperature range	Tstg	-55~+125	deg. C

4. CHARACTERISTICS

4-1 ELECTRICAL CHARACTERISTICS

Item	Cumhal	Electrical Specification				
	Symbol	Condition	Min	Тур.	Max	Unit
Nominal Frequency	fo	Ta = 25 deg. C		32.768		kHz
Frequency Tolerance	df/fo	Ta = 25 deg.C	-20		20	ppm
Load Capacitance	CL			6.0		pF
Equivalent series resistance	R1				60	kΩ
Q-Value	Q		13000			
Motional capacitance	C1		3.0		4.4	fF
Shunt capacitance	Co		0.6		1.2	pF
Turning point	Тр		20		30	deg. C
Secondary temperature Coefficient	K		-4.0			10 ⁻⁸ /degC ²
Aging	df/F	Ta = 25 deg. C	-3		3	ppm/year
Drive level	DL			0.1	0.5	μW
Insulation resistance (between electrodes)	IR		500			ΜΩ

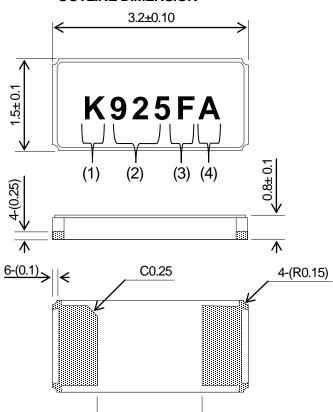
4-2 MOISTURE SENSITIVITY LEVEL

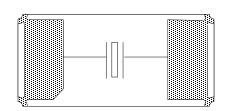
Level 1

5. APPEARANCES, PHYSICAL DIMENSION

OUTLINE DIMENSION

CONNECTION (TOP VIEW)





UNIT:mm

MARKING

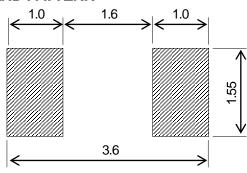
1 Identification K

1.70

- 2 Date Code(3 Digits) Last 1 digit of year and week Code.
- 3 Load Capacitance (Example) 6.0pF → F
- 4 Management number Alphabet or Number 1 digit.

*The font of marking above is for reference purpose.

6. RECOMMENDED LAND PATTERN



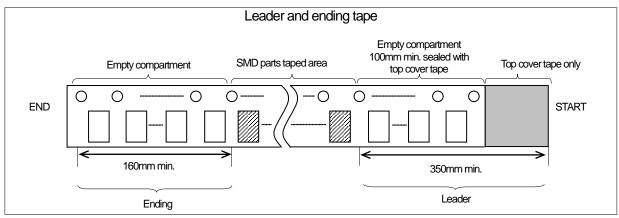
UNIT: mm

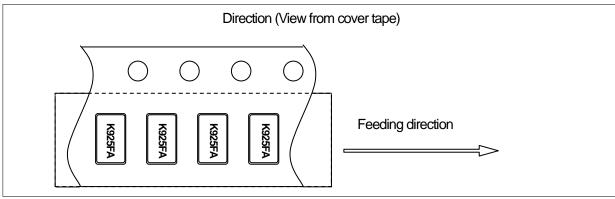
7. TAPING

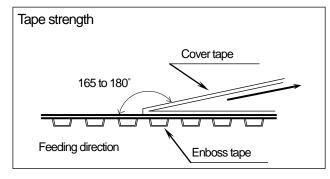
7.1 TAPING

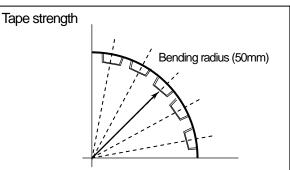
Maximum quantity per 1 reel is Max 3,000pcs(\$\phi\$180 Reel) and oriented part in 1 direction

- 1. Material of the carrier tape shall be polystyrene or A-PET (ESD).
- 2. Material of the seal tape shall be polyester (ESD).
- 3. The seal tape shall not cover the sprocket holes and not protrude from the carrier tape.
- 4. The R of the corner without designation is 0.2R MAX.
- 5. Misalignment between centers of the cavity and a sprocket hole shall be 0.05mm or less.
- 6. Cumulative pitch tolerance of "G" shall be ±0.2mm at 10 pitches.
- 7. The directivity of printing in an embossing tape shall be unified as shown in the above-mentioned figure.
- 8. Peeling force of the seal tape is in the range of 0.1 to 0.7N.

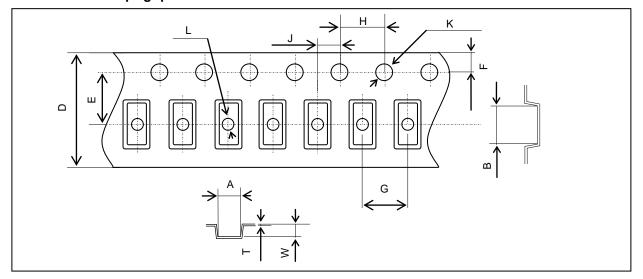








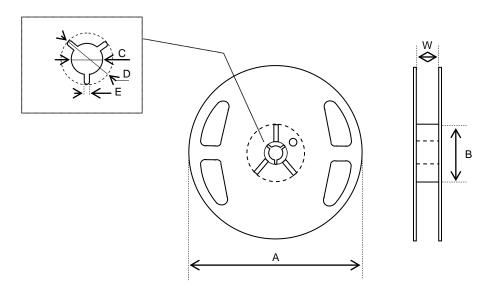
7-2 Emboss Taping specifications



symbol	А	В	D	Е	F	G
Dimension	1.8±0.1	3.6±0.1	12.0±0.3	5.5±0.1	1.75±0.1	4.0±0.1
Symbol	Н	J	K	L	W	Т
Dimension	4.0±0.1	2.0±0.1	1.5+0.1/-0	1.0+0.1/-0	1.0±0.1	0.3±0.05

(Unit: mm)

7-3 Reel specifications



Symbol	Α	В	С
Dimension	φ180 +0/-1.5	ф60 +1.0/-0	φ13±0.2
Symbol	D	E	W
Dimension	φ21±0.8	2.0±0.5	13.0 +1.0/-0

(Unit: mm)

8. RELIABILITY

Frequency Stability and ESR Stability After stressing.

TEST ITEM		Frequency Stability	ESR Stability	Remarks
		(ppm)	(%)	
8.1	Low temp. use/storage	±5		
8.2	High temp. use/storage	±5		
8.3	Shock	± 20		
8.4	Vibration	±5	L 20	To 25 dog C
8.5	Soldering iron resistance	±5	± 30	Ta=25 deg. C
8.6	Manual hot gas resistance	±10		
8.7	High temp. With humidity	±5		
8.8	Temperature cycle	±5		

9. REFLOW PROFILE

Pb-free reflow requirements for soldering heat resistance

